

Baimei Tan

List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/8855577/publications.pdf>

Version: 2024-02-01

35
papers

425
citations

687363

13
h-index

794594

19
g-index

35
all docs

35
docs citations

35
times ranked

208
citing authors

#	ARTICLE	IF	CITATIONS
1	Corrosion control of copper wiring by barrier CMP slurry containingazole inhibitor: Combination of simulation and experiment. Colloids and Surfaces A: Physicochemical and Engineering Aspects, 2020, 599, 124872.	4.7	44
2	Effect of arginine-based cleaning solution on BTA residue removal after Cu-CMP. Colloids and Surfaces A: Physicochemical and Engineering Aspects, 2020, 586, 124286.	4.7	36
3	A study of FTIR and XPS analysis of alkaline-based cleaning agent for removing Cu-BTA residue on Cu wafer. Surface and Interface Analysis, 2019, 51, 566-575.	1.8	28
4	Theoretical and electrochemical analysis on inhibition effect of benzotriazole and 1,2,4-triazole on cobalt surface. Colloids and Surfaces A: Physicochemical and Engineering Aspects, 2020, 591, 124516.	4.7	28
5	Synergistic effect of composite complex agent on BTA removal in post CMP cleaning of copper interconnection. Materials Chemistry and Physics, 2020, 252, 123230.	4.0	27
6	Application of surfactant for facilitating benzotriazole removal and inhibiting copper corrosion during post-CMP cleaning. Microelectronic Engineering, 2018, 202, 1-8.	2.4	24
7	Experimental validation and molecular dynamics simulation of removal of PO residue on Co surface by alkaline cleaning solution with different functional groups. Colloids and Surfaces A: Physicochemical and Engineering Aspects, 2021, 610, 125932.	4.7	19
8	Toward Understanding the Adsorption And Inhibition Mechanism of Cu-MBTA Passivation Film on Copper Surface: A Combined Experimental and DFT Investigation. Electronic Materials Letters, 2021, 17, 109-118.	2.2	18
9	Theoretical and electrochemical analysis on inhibition effects of benzotriazole derivatives (un- and Tj ETQq1 1 0.784314 rgBT /Overlo	3.6	16
10	Study on the Adsorption and Inhibition Mechanism of 1,2,4-Triazole on Copper Surface in Copper Interconnection CMP. ECS Journal of Solid State Science and Technology, 2019, 8, P313-P318.	1.8	15
11	Multidimensional insights into the corrosion inhibition of potassium oleate on Cu in alkaline medium: A combined Experimental and theoretical investigation. Materials Science and Engineering B: Solid-State Materials for Advanced Technology, 2021, 272, 115330.	3.5	15
12	The effect of structural properties of benzo derivative on the inhibition performance for copper corrosion in alkaline medium: Experimental and theoretical investigations. Colloids and Surfaces A: Physicochemical and Engineering Aspects, 2022, 649, 129531.	4.7	15
13	Non-ionic surfactant on particles removal in post-CMP cleaning. Journal of Semiconductors, 2015, 36, 026002.	3.7	13
14	Synergistic effect of LABSA/JFCE combined surfactant system on the removal of particles on copper wafer surface. Materials Chemistry and Physics, 2021, 257, 123841.	4.0	12
15	Effects of Novel Inhibitor on Galvanic Corrosion of Copper and Cobalt and Particle Removal. ECS Journal of Solid State Science and Technology, 2019, 8, P545-P552.	1.8	11
16	Adsorption Mechanism of Potassium Oleate on Cobalt Surface Based on Cobalt Interconnection CMP: A Combined Experimental and DFT Investigation. ECS Journal of Solid State Science and Technology, 2021, 10, 024003.	1.8	11
17	Effect of EDTA-based alkaline cleaning solution on TAZ removal in post CMP cleaning of copper interconnection. Materials Research Bulletin, 2021, 137, 111202.	5.2	10
18	Unraveling the surface behavior of amino acids on Cu wiring in chemical mechanical polishing of barrier layers: A combination of experiments and ReaxFF MD. Journal of Molecular Liquids, 2021, 341, 117307.	4.9	10

#	ARTICLE	IF	CITATIONS
19	Role of Penetrating Agent on Colloidal Silica Particle Removal during Post Cu CMP Cleaning. ECS Journal of Solid State Science and Technology, 2018, 7, P380-P384.	1.8	9
20	Effect of Corrosion Inhibitor BTA on Silica Particles and their Adsorption on Copper Surface in Copper Interconnection CMP. ECS Journal of Solid State Science and Technology, 2022, 11, 044002.	1.8	8
21	Effect of organic amine alkali and inorganic alkali on benzotriazole removal during post Cu-CMP cleaning. Journal of Semiconductors, 2018, 39, 126003.	3.7	7
22	Composite complex agent based on organic amine alkali for BTA removal in post CMP cleaning of copper interconnection. Journal of Electroanalytical Chemistry, 2022, 910, 116187.	3.8	7
23	Synergetic Effect of 5-Methyl-1H-Benzotriazole and Sodium Dodecyl Benzene Sulfonate on CMP Performance of Ruthenium Barrier Layer in KIO ₄ -Based Slurry. ECS Journal of Solid State Science and Technology, 2020, 9, 104005.	1.8	6
24	Effect of ethylenediamine on CMP performance of ruthenium in H ₂ O ₂ -based slurries. RSC Advances, 2021, 12, 228-240.	3.6	6
25	A novel cleaner for colloidal silica abrasive removal in post-Cu CMP cleaning. Journal of Semiconductors, 2015, 36, 106002.	3.7	5
26	Thermal Stability Study of GaP/High- κ Dielectrics Interfaces. Advanced Materials Interfaces, 2017, 4, 1700609.	3.7	5
27	Removal of Nanoceria Abrasive Particles by Using Diluted SC1 and Non-Ionic Surfactant. ECS Journal of Solid State Science and Technology, 2021, 10, 034010.	1.8	5
28	Effect of Intermolecular Interaction of Compound Surfactant on Particle Removal in Post-Cu CMP Cleaning. ECS Journal of Solid State Science and Technology, 2021, 10, 064007.	1.8	5
29	Optimization of cleaning process parameters to remove abrasive particles in post-Cu CMP cleaning. Journal of Semiconductors, 2018, 39, 126002.	3.7	4
30	Influence of diamond wire saw slicing parameters on (010) lattice plane beta-gallium oxide single crystal wafer. Materials Science in Semiconductor Processing, 2021, 133, 105939.	4.0	4
31	Study on Different Surfactants for Post CMP Cleaning of Novel Barrier. , 2019, , .		1
32	Unraveling the Mechanism of Removing NA Contamination by TMAH-Based Cleaning Solution During Post Co-CMP Cleaning. ECS Journal of Solid State Science and Technology, 2022, 11, 034005.	1.8	1
33	Study on Infrared Spectrum Detection and Analysis of BTA Residual after Copper CMP. , 2019, , .		0
34	Eco-friendly Corrosion Inhibitors for Multilevel Metal Interconnects of Integrated Circuits. ACS Symposium Series, 0, , 149-165.	0.5	0
35	Corrosion inhibitors for Cu chemical mechanical planarization (CMP). , 2022, , 155-170.		0